

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-22. (Canceled).

23. (Previously Presented) A method of making an interconnectable package comprising:
providing a first wafer having a plurality of bottom die;
providing a second wafer having a plurality of top die;
patterning at least one transmission line on at least one side of said bottom die of said first wafer;
etching at least one integral connector and at least one transmission line on said top die of said second wafer;
coupling a component to each of said plurality of bottom die of said first wafer;
forming a wafer stack by bonding said second wafer to said first wafer such that said top die of said second wafer is aligned with said bottom die of said first wafer; and
dicing said wafer stack into a plurality of individual packets wherein each of said plurality of packets contains a top die having said integral connector bonded to said bottom die having a component.

24. (Previously Presented) The method of making an interconnectable package of claim 23, further comprising: etching an aperture in said top die of said second wafer such that said

component may be placed through said aperture and coupled to said bottom die of said second wafer after the bonding and dicing of said first and second wafer.

25. (Previously Presented) The method of making an interconnectable package of claim 23 wherein a cap is bonded over said aperture after said component is placed through said aperture.

26. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the component is an integrated circuit.

27. (Previously Presented) The method of making an interconnectable package of claim 26, wherein the integrated circuit is a millimeter microwave integrated circuit.

28. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the component is an optical fiber.

29. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the component is an optical semiconductor.

30. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the integral connector etched on said die of said second wafer is shaped as a male connection component.

31. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a female connection component.

32. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a hermaphrodite connection component.

33. (Previously Presented) The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a female connection component.

34. (Currently Amended) A method of making a dielectric package for housing a component and having an integral connection component comprising:

providing a first die, said first die having an integral planar connection member and having at least one conductor patterned on said first die;

providing a second die having at least one conductor patterned on said second die; and

bonding said second die to said first die such that the conductor on said first die is aligned with said conductor on said second die and said integral connection member on said first die ~~forms~~ connects to said second die in a coplanar state thus forming a planar connection component for said dielectric package.

35. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the single connection component is formed having a male shape.

36. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the single connection component is formed having a female shape.

37. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 36, further comprising:
coupling a component to said first die prior to bonding the second die to said first die.

38. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, further comprising:
etching an aperture into said second die.

39. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 38, wherein a component is placed through said aperture on said second die and coupled to said first die after the second die is bonded to the first die.

40. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an integrated circuit.

41. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 40, wherein the integrated circuit is a millimeter microwave integrated circuit.

42. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an optical fiber.

43. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an optical semiconductor.

44. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the dielectric package has a plurality of connection components.

45. (Previously Presented) The method of making a dielectric package for housing a component and having an integral connection member of claim 44, wherein the dielectric

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package having plurality of connection components includes both female and male shaped connection components.